

Title (en)

SYSTEM FOR COOLING AN INTEGRATED CIRCUIT WITHIN A COMPUTING DEVICE

Title (de)

SYSTEM ZUR KÜHLUNG EINER INTEGRIERTEN SCHALTUNG IN EINER BERECHNUNGSVORRICHTUNG

Title (fr)

SYSTÈME PERMETTANT DE REFROIDIR UN CIRCUIT INTÉGRÉ DANS UN DISPOSITIF INFORMATIQUE

Publication

**EP 2973689 A1 20160120 (EN)**

Application

**EP 14774761 A 20140219**

Priority

- US 201361786300 P 20130314
- US 2014017184 W 20140219

Abstract (en)

[origin: WO2014158481A1] One variation of a system for cooling an electrical component within a computing device - including a digital display - includes: an internal heatsink thermally coupled to the integrated circuit and defining a fluid passage including a first end and a second end; a heat exchange layer arranged across a viewing surface of the digital display, including a transparent material, and defining a fluid channel extending across a portion of the digital display, the fluid channel including a fluid inlet coupled to the first end of the fluid passage and a fluid outlet coupled to the second end of the fluid passage; a transparent fluid; and a displacement device configured to circulate the transparent fluid between the internal heatsink and the fluid channel.

IPC 8 full level

**G02F 1/1333** (2006.01); **G06F 1/20** (2006.01); **G06F 3/01** (2006.01); **H01L 23/473** (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP)

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Designated contracting state (EPC)

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Designated extension state (EPC)

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DOCDB simple family (publication)

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